



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE2B165		<b>Issued</b>		17. June 2016		
<b>MA#</b>		MA001118736						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		557.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.846	0.87	0.87	8691	8691
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7707	
wire	non noble metal	copper	7440-50-8	174.475	31.30	32.12	312956	321144
	noble metal	gold	7440-57-5	0.185	0.03	0.03	332	332
	encapsulation	organic material	carbon black	1333-86-4	1.089	0.20		1953
encapsulation	plastics	epoxy resin	-	35.205	6.31		63147	
	inorganic material	silicondioxide	60676-86-0	326.641	58.59	65.10	585898	650998
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13445	13445
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1427	1427
glue	plastics	epoxy resin	-	0.331	0.06		594	
	noble metal	silver	7440-22-4	1.878	0.34	0.40	3369	3963
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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